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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of: Pai-Hung Pan

Serial No.: To be assigned

Filed: May 5, 1998

For: TECHNIQUE FOR FORMING
SHALLOW TRENCH ISOLATION
STRUCTURE WITHOUT CORNER
EXPOSURE AND RESULTING
STRUCTURE

Examiner: To be assigned

Group Art Unit: To be assigned

Attorney Docket No.: 2919.1US
(96-0499.01)

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INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability

as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

DOCUMENTS

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Issue Date</u>
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Other Documents

Davari, et al., "A Variable-Size Shallow Trench Isolation (STI) Technology With Diffused Sidewall Doping For Submicron CMOS", *IEEE IEDM* (1988).

K. Blumenstock et al., "Shallow Trench Isolation for Ultra-Large-Scale Integrated Devices", *J. Vac. Sci. Technol.*, B 12(1) (Jan/Feb 1994).

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Information Disclosure Statement is filed within three (3) months of the filing date of the above-identified application, and no certification pursuant to 37 C.F.R. § 1.97(c) or a fee pursuant to 37 C.F.R. 1.17(p) is required.

Respectfully submitted,



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Date: May 5, 1998

Enclosures: Form PTO-1449

Copy of documents cited

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